

**PATENT NUMBER and
ISSUE DATE**

U.S. UTILITY Patent Application

APPL NUM 10063573	FILING DATE 05/03/2002	CLASS 228	SUBCLASS 180-22	GAU 1725	EXAMINER Edmondson
**APPLICANTS: Tong Ho-Ming; Lee Chun-Chi; Fang Jen-Kuang; Huang Min-Lung; Chen Jau-Shoung; Su Ching-Huei; Weng Chao-Fu; Lee Yung-Chi;					
**CONTINUING DATA VERIFIED: <i>None - LRG</i>					
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** FOREIGN APPLICATIONS VERIFIED: TAIWAN 91102992 02/21/2002					
PG-PUB	DO NOT PUBLISH <input type="checkbox"/>	RESCIND <input type="checkbox"/>			
Foreign priority claimed <input checked="" type="checkbox"/> yes <input type="checkbox"/> no 35 USC 119 conditions met <input type="checkbox"/> yes <input type="checkbox"/> no Verified and Acknowledged Examiners's initials				ATTORNEY DOCKET NO 8385-US-PA	
TITLE : Bump manufacturing method					

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NOTICE OF ALLOWANCE MAILED		Assistant Examiner	CLAIMS ALLOWED		
			Total Claims	Print Claim for O.G.	
ISSUE FEE		Primary Examiner	DRAWING		
Amount Due	Date Paid		Sheet Drawn	Page Count	Print Fee
		PREPARED FOR ISSUE	Application Examiner		
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